

/ Descriptions

TO-251 N MOS N-CHANNEL MOSFET in a TO-251 Plastic Package.

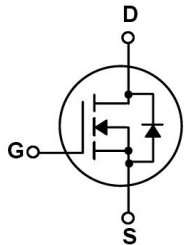
/ Features

Low thermal resistance, fast switching.

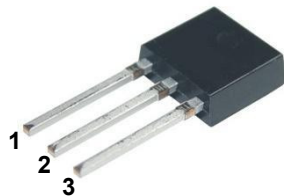
/ Applications

For Electronic transformer, Switch mode power supply.

/ Equivalent Circuit



/ Pinning



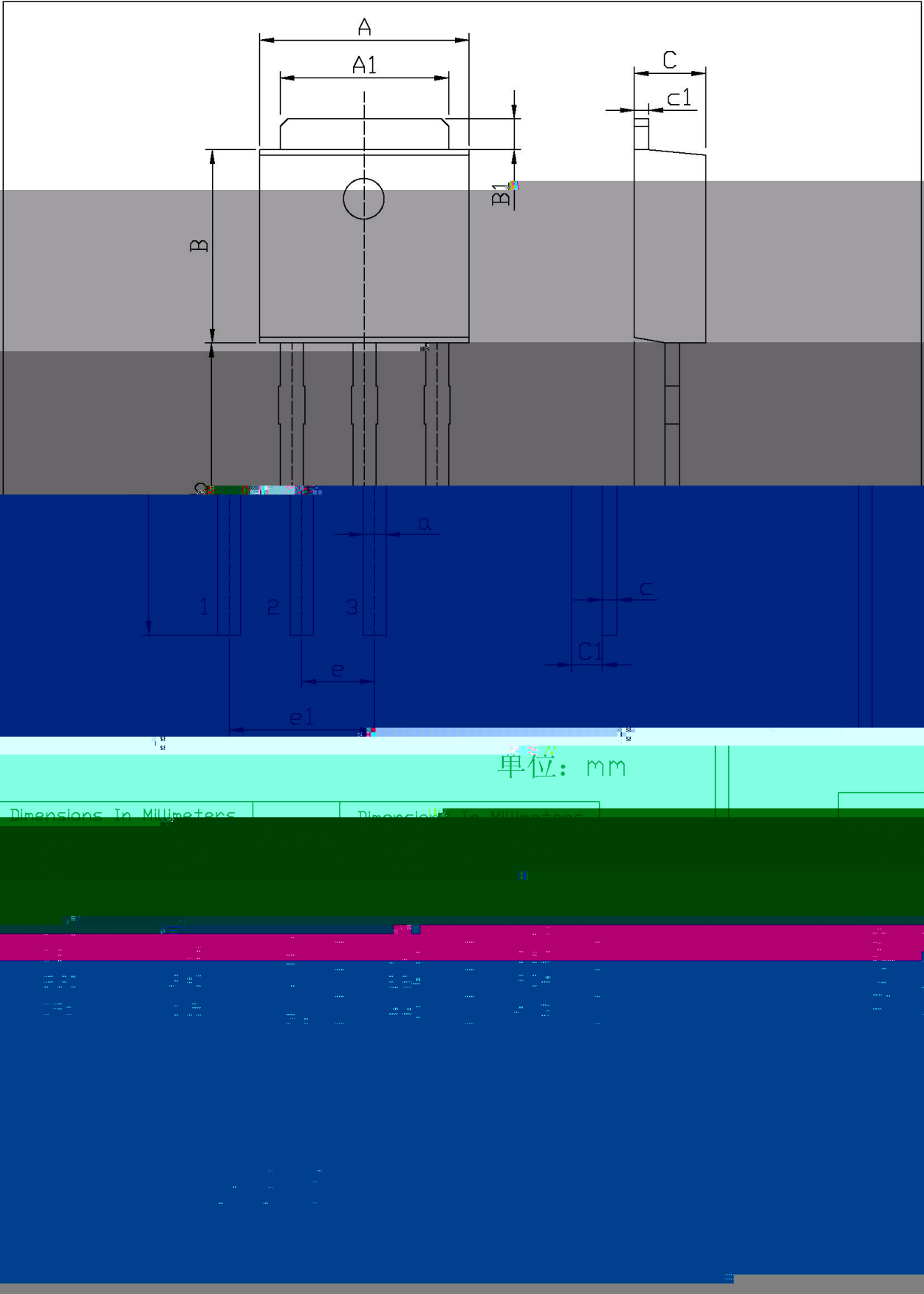
PIN1 G PIN 2 D PIN 3 S

/ h_{FE} Classifications & Marking

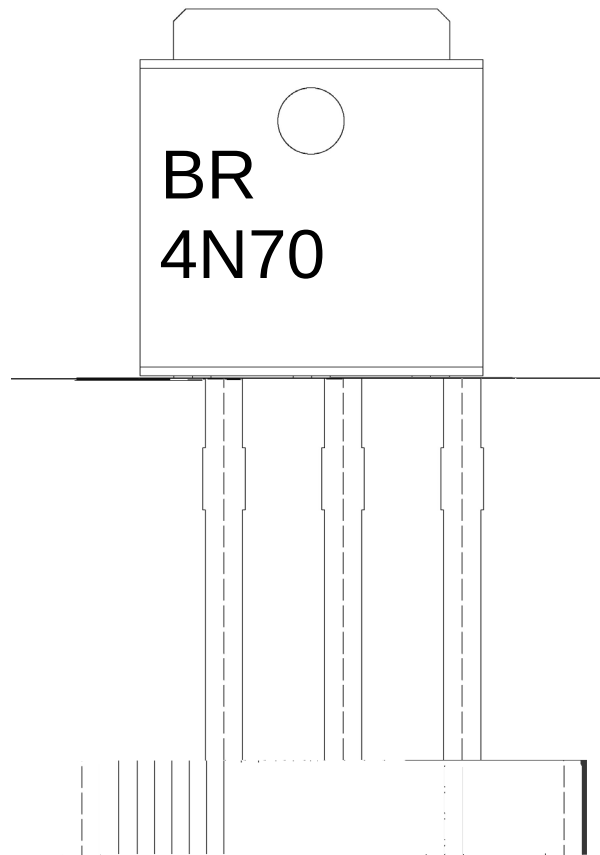
See Marking Instructions.

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	700	V
Gate-Source Voltage	V_{GS}	± 30	V
Drain Current	$I_D(T_c=25^\circ\text{C})$	4.0	A
Drain Current	$I_D(T_c=100^\circ\text{C})$	2.5	A
Drain Current - Pulsed	I_{DM}	16	A
Single Pulsed Avalanche Energy	E_{AS}	260	mJ
Power Dissipation	P_{tot}	106	W
Junction Temperature Range	T_j	150	
Storage Temperature Range	T_{stg}	-55~150	
Thermal Resistance Junction-case	$R_{\theta-JC}$	1.18	/W
Thermal Resistance Junction-ambient	$R_{\theta-JA}$	62.5	/W

/ Package Dimensions



/ Marking Instructions



BR

Note:

BR: Company Code

: Product Type.

****: Lot No. Code, code change with Lot No.

() / Temperature Profile for Dip Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-----|-----|----|----------|---|
| 1 | 25 | 150 | 60 | 90sec; | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 255 | 5 | 5 | 0.5sec; | 2.Peak Temp.:255 5 , Duration:5 0.5sec. |
| 3 | | | 2 | 10 /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

270 5 10 1 sec. Temp.:270±5 Time:10±1 sec

/ Packaging SPEC.

/ BULK

Package Type	Units					Dimension (unit mm ³)		

/ TUBE

Package Type	Units					Dimension (unit mm ³)		

/ Notices